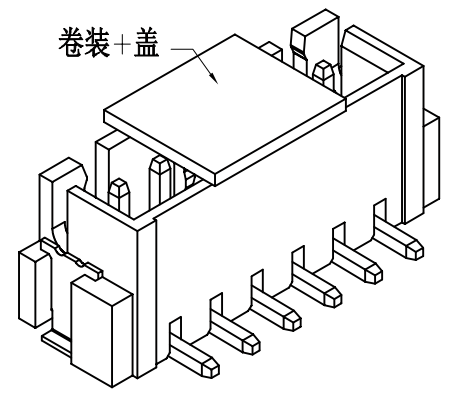
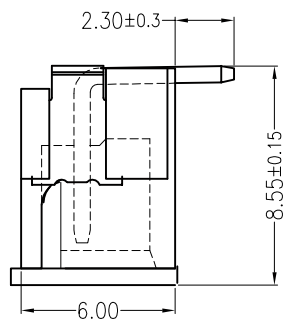
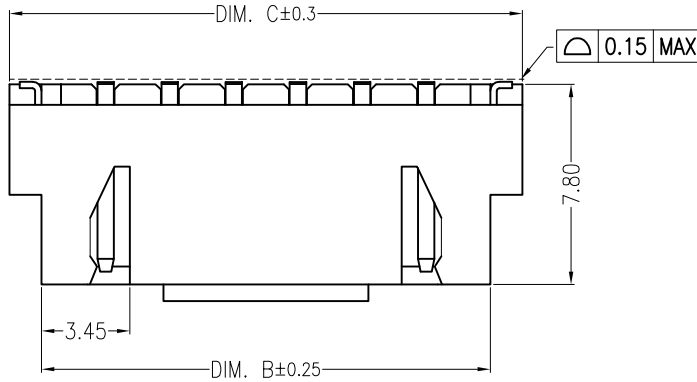
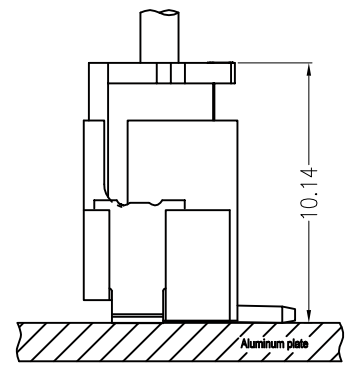
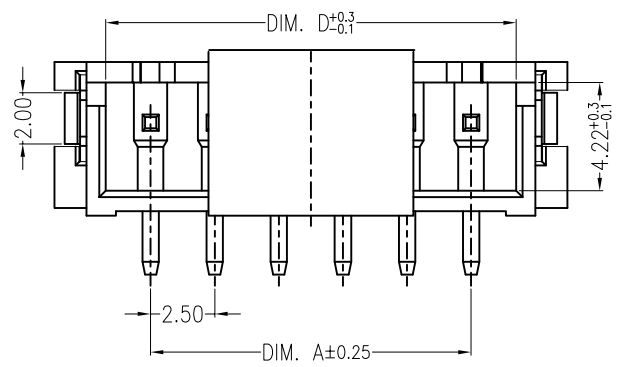


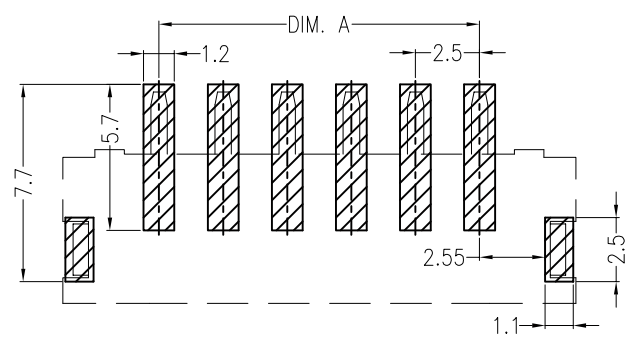
REV	ECN No.	DESCRIPTION	DESIGN	DATE
AO		Release		2016.05.19



Main Specifications
 Poles: 02 to 16
 Contact resistance: $\leq 20\text{m}\Omega$
 Insulation resistance: $\geq 1000\text{M}\Omega$
 Rated voltage: 250V AC DC
 Rated current: 3.0A AC DC
 Withstand Voltage: 1000V AC/minute
 Temperature Range: $-25^{\circ}\text{C} \sim +105^{\circ}\text{C}$



Assembly Layout



SUGGESTED PCB LAYOUT

Circuit	Dimensions (mm)			
	DIM. A	DIM. B	DIM. C	DIM. D
02	2.50	7.50	10.00	6.00
03	5.00	10.00	12.50	8.50
04	7.50	12.50	15.00	11.00
05	10.00	15.00	17.50	13.50
06	12.50	17.50	20.00	16.00
07	15.00	20.00	22.50	18.50
08	17.50	22.50	25.00	21.00
09	20.00	25.00	27.50	23.50
10	22.50	27.50	30.00	26.00
11	25.00	30.00	32.50	28.50
12	27.50	32.50	35.00	31.00
13	30.00	35.00	37.50	33.50
14	32.50	37.50	40.00	36.00
15	35.00	40.00	42.50	38.50
16	37.50	42.50	45.00	41.00

C	SOLDER TAB	2 PCS	PhosphorBronze	Sn-plated
B	CONTACT	2~16 PCS	Brass	Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH

LEDsconn			TITLE: 2.5mmPITCH 180°WAFER SMT TYPE	
X.±0.5	X.±5°	USE: CUSTOMER	PART NO.:	
.X±0.3	.X±2°	APPD: 邵敬和	DWG NO.:	
.XX±0.25	.XX±1°	CHKD: 田峰	SCALE 1 : 1	
--	--	DR: 吴丹平	SHEET 1 / 1	
UNITS: mm				